

ROITHNER LASERTECHNIK GMBH

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SMB1N-550H-02



- 550 nm, 100 mW
- InGaAs chip, 1000 x 1000 µm
- **PA9T SMD package**
- Beam Angle: ± 10°



Description



SMB1N-550H-02 is a surface mount InGaN based high power green LED, with a typical peak wavelength of 550 nm and optical output power of 100 mW @ 350 mA. It comes in polyamide resin SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and silicone resin molded lens. Additional variants with different beam angles are available on request.

Maximum Ratings*

Parameter	Cumbal	Va	Hmit		
Faranietei	Symbol	Min.	Max.	Unit	
Power Dissipation	PD		1200	mW	
Forward Current	l _F		350	mA	
Pulse Forward Current **	I FP		500	mA	
Reverse Voltage	UF		5	V	
Thermal Resistance	RTHJA		10	K/W	
Junction Temperature	TJ		120	°C	
Operating Temperature	TCASE	- 40	+ 100	°C	
Storage Temperature	T _{STG}	- 40	+ 100	°C	
Lead Solder Temperature (t _{max} . 5s)	T _{SLD}		+ 250	°C	

^{*}Operating close to or exceeding these parameters may damage the device

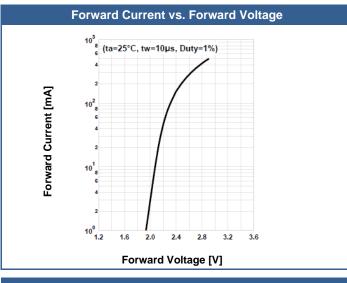
Electro-Optical Characteristics (TCASE = 25°C)

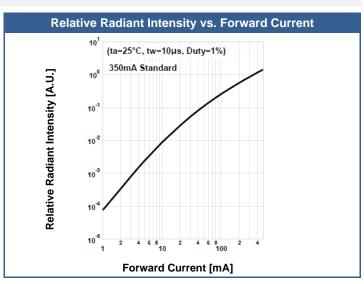
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =350 mA	540		560	nm
Half Width	λ_{Δ}	I _F =350 mA		35		nm
Forward Voltage	VF	I _F =350 mA		2.7	3.4	V
	V _{FP}	I _{FP} =500 mA		2.9		
Total Radiated Power	Po	$I_F=350 \text{ mA}$	70	100		mW
		I _{FP} =500 mA		140		
Radiant Intensity	I _E	I _F =350 mA		160		mW/sr
		I _{FP} =500 mA		220		
Viewing Angle	2θ _{1/2}	I _F =100 mA		20		deg.
Rise Time	t r	I _F =350 mA		100		ns
Fall Time	t f	I _F =350 mA		30		ns

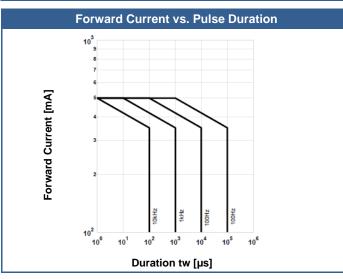
^{*} duty cycle = 1 %, pulse width = 10 μ s

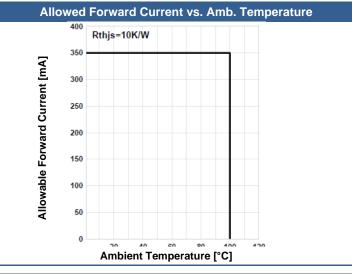
^{**} duty cycle = 1 %, pulse width = 10 μ s

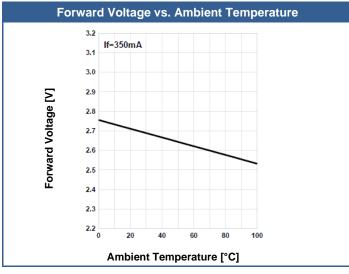
Typical Performance Curves

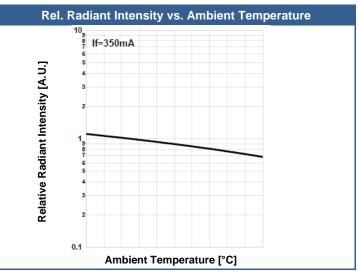




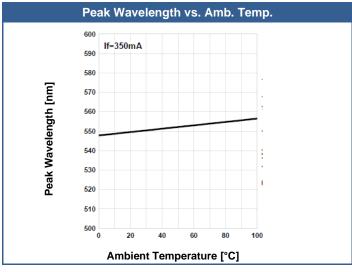


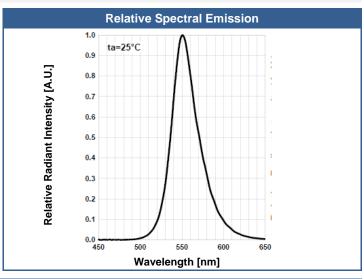


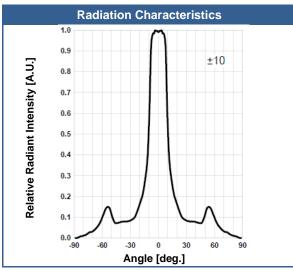


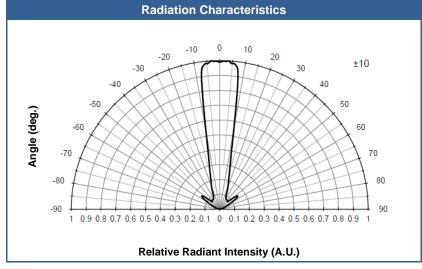


Typical Performance Curves

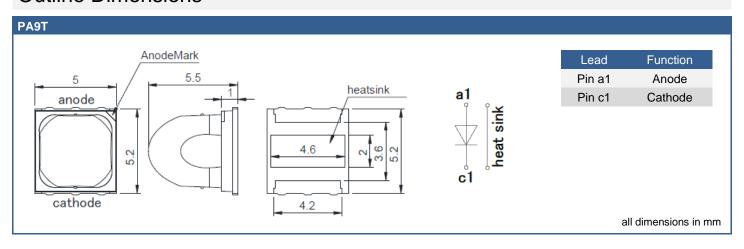








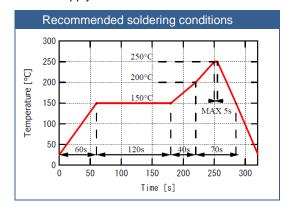
Outline Dimensions

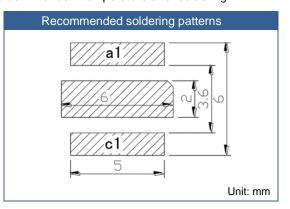


General Notes

Soldering

- · Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- . Do not apply current to the LED until it has cooled down to room temperature after soldering





Cleaning

- . Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended
- DO NOT USE acetone, chloroseen, trichloroethylene, or MKS
- DO NOT USE ultrasonic cleaners

Static Electricity

- LEDs are sensitive to electrostatic discharge (ESD).
- Precautions against ESD must be taken when handling or operating these LEDs
- Surge voltage or electrostatic discharge can result in complete failure of the LED.

Radiation

- During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer.
- · Do avoid exposure to the emitted light. Protective glasses if needed
- It is further advised to attach a warning label on products/systems.

Operation

- · Do only operate LEDs with a current source.
- Running these LEDs from a voltage source will result in complete failure of the device.
- Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

Storage

- The maximum shelf life of LEDs in the originally sealed aluminum bag is 12 months.
- Before opening the aluminum bag, please store it at <30 °C, <60 % RH.
- After opening the aluminum bag, please solder the LEDs within 72 hours (floor life) at 5 − 30 °C, <50 % RH.
- Put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.

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